

MEMORANDUM OF UNDERSTANDING

This Memorandum of Understanding (the "MOU") is entered into on this 8th day of July 2026, by and between Sri Chandrasekharendra Saraswathi Viswa Maha Vidyalyaya, a Deemed to be University under Section 3 of UGC Act, 1956 and having its office at Sri Jayendra Saraswathi Street, Enathur, Kanchipuram-631561, Tamilnadu, India (herein after referred to as "SCSVMV", which term shall wherever the context so admits mean and include their legal representatives, executors, administrators, agents and assigns) of the One Part,

And

WaferLead Pte. Ltd. having its registered office at 10 Anson Road, #17-18 International Plaza, Singapore 079903 hereinafter referred to as "WaferLead", (which expression shall, unless repugnant to the context or meaning thereof, be deemed to mean and include its successors and permitted assigns) of the Other Part.

SCSVMV and WaferLead are hereinafter collectively referred to as Parties and individually as separately identified.

WHEREAS SCSVMV is a multi-disciplinary institution offering Under Graduation, Post Graduation and Ph.D courses in various streams including Sanskrit, Engineering, Commerce, Management, Science, Education, Allied Health Sciences, Law and Ayurveda.

AND WHEREAS WaferLead Pte. Ltd. Is a limited liability company registered in Singapore to develop, manufacture and sale of SiC wafers and equipment that requires to make SiC wafers.

AND WHEREAS the Parties desire to collaborate in the areas of research, education, training, innovation, and technology development.

NOW THEREFORE, the Parties hereby agree as follows:

1. OBJECTIVES

The purpose of this MOU is to establish a framework for collaboration between the Parties in the field of Compound Semiconductor Technology, with an initial focus on Silicon Carbide (SiC) semiconductor materials, devices, applications, and related technologies.

SCSVMV with WaferLead as the Industry Partner shall carry on Joint Research, Development and Deployment Project(s) to

- (i) Develop and manufacture industrial PVT furnaces to grow SiC boules for SiC wafer products and applications.



- (ii) SiC wafer fabrication equipment and process, including epitaxial growth, wafer evaluation and testing.
- (iii) Technology transfer from Waferlead Singapore and training of personnel
- (iv) Semiconductor process knowledge and manufacturing process sharing (from SCSVMV Enathur Kanchipuram, India)

2. RESPONSIBILITIES OF SCSVMV

SCSVMV will provide adequate on-site space for equipment and product development, testing, and small-scale manufacturing. Additionally, SCSVMV will supply essential utilities—including electricity, water, gases, and chemicals—required for successful project completion. To facilitate hands-on learning, SCSVMV students will be employed to work alongside WaferLead, gaining direct experience with equipment and process technologies throughout the project

3. RESPONSIBILITIES OF WAFERLEAD

WaferLead will provide the necessary technology to manufacture crystal growth furnaces and to produce silicon carbide (SiC) boules and wafers up to 200mm in diameter. This process technology encompasses the production of both n-type and semi-insulating SiC. Additionally, WaferLead will develop epi-SiC wafers specifically tailored for high-voltage MOSFET fabrication.

4. FINANCE

- 1. This MOU places no financial/legal obligations or supplementary commitments on either party and is an intent to collaborate
- 2. Financial arrangements, if any, for each specific project agreed under this MOU, will be decided mutually, on a case to case basis, and brought on record in each case after due approval from the competent authorities of the Parties.
- 3. In any of the projects, wherever financial aspects are involved, amount, payment conditions, etc would be spelt out clearly by the parties and will be recorded in a separate definitive agreement, before starting a project.

5. NON-BINDING NATURE



This MoU is intended to provide a framework for collaboration and does not create any legally enforceable financial or commercial obligations except those expressly stated relating to confidentiality, intellectual property, dispute resolution, and other provisions intended to survive.

6. CONFIDENTIALITY

Each party shall maintain complete confidentiality of any information of the other, disclosed during the term of this MoU ("Confidential Information"), either directly or indirectly in any form whatsoever including, but not limited to, in writing, in machine readable or other tangible form, orally or visually (subsequently reduced to writing). Both parties undertake to (i) hold all such confidential information in strictest confidence, (ii) not to disclose such confidential information either in whole or in part to any person other than those of its officers, employees and agents who need to know the confidential information for the purpose authorized hereunder provided that each such officer, employee or agent has agreed in writing to maintain confidentiality of the information for any purpose whatsoever save as may be strictly necessary for the performance of this MoU. This clause pertaining to confidentiality shall survive the term of this MoU and remain in full force and effect not withstanding any termination of this MoU.

7. INTELLECTUAL PROPERTY RIGHTS

IPR titles or ownership of any products, proprietary information or technology tools, processes, utilities and methodology including any Proprietary products or components thereof used hereunder or development of any deliverables and all new ideas , inventions, innovations, or developments conceived, developed, contributed, distributed or made by either party hereunder, and all customization, enhancement and modifications thereof, will not be transferred from one party to on account of use of the same as part of any work under this MoU and shall always remain with the originating partner. In case of ideas that are jointly identified and developed, the IPR will be shared by both the parties, and such cases will be agreed upon from time to time mutually.

8. TERM AND TERMINATION

1. This MOU will be in force for the period of 2 years from the date of signing, after which period, the MoU may be renewed with mutual consent of both the parties



2. Either party can cancel or terminate this MoU unilaterally (and without reason), by giving an advance written notice of one month to the other.
3. Termination of this Agreement shall not adversely affect or interrupt any ongoing project initiated prior to the date of termination, and all such projects shall continue until completion in accordance with the terms of this Agreement.

9. NOTICES

All Notices, requests, demands and other communications under this MoU or in connection herewith shall be given to or made upon the respective parties as follows

Dr. Harikrishnan R
Professor of Chemistry
Director of Sri Jayendra Saraswathi Centre of Advanced Research (SJSCAR)
Sri Chandrasekharendra Saraswati Viswa Mahavidyalaya
Jayendra Saraswathi Street
Enathur, Kanchipuram – 631 561
Ph: +91 7358299894
ramananhhk@kanchiuniv.ac.in
director.sjscar@kanchiuniv.ac.in

Dr. Sunil Wickramanayaka
Chief Executive Officer
WaferLead Pte. Ltd.
10 Anson Road, #17-18 International Plaza
Singapore 079903
DID: (65) 6423 1487
HP: (65) 9008 2604
Email: s.wickramanayaka@waferlead.com

Or to such other person or addresses as any of the Parties shall have notified to the others. All Notices, requests, demand and other communications given or made in accordance with the provisions of this MoU shall be in writing by letter/email to the intimated mail ids.

10. MISCELLANEOUS

Neither this MoU, nor any activities described herein, shall be construed as creating a partnership, joint venture, agency or other such relationship. Both parties agree that this MoU represents a non- exclusive relationship between the



parties, and nothing contained herein shall preclude either party from participating/initiating similar relationship with third parties.

This MOU shall not be amended without the prior written consent of both parties.

11. FORCE MAJEURE

No Party shall be liable or responsible to the other Party, nor be deemed to have defaulted under or breached this Agreement, for any failure or delay in fulfilling or performing any term of this MOU by reason of:

1. Fire, explosion, cyclone, floods, droughts, earthquakes, epidemics.
2. War, revolutions, acts of public enemies, blockage or embargo, riots and civil commotion.
3. Any law, order, proclamation, ordinance or requirements of any government or authority or representative of any such government, including restrictive trade practices or regulations.
4. Strikes, shutdowns or labour disputes which are not instigated for the purpose of avoiding obligations herein.

Any other circumstances beyond the reasonable control of the party affected shall be excused from its performance to the extent such performance related to prevention, restrictions, delay or interference and provided the party so affected used its best efforts to remove such cause of non-performance, and when removed the party shall continue performance with the utmost dispatch.

Each of the parties agrees to give written notice to the other party upon becoming aware of an event of Force Majeure and mentioning details of the circumstance giving rise to the Event of Force Majeure.

12. REPRESENTATIONS AND WARRANTIES

Each Party represents and warrants that:

- (1) It has full authority to enter into this Agreement.
- (2) It has no conflicting commitments that impede performance under this Agreement.
- (3) It possesses all required licenses, expertise, and infrastructure to fulfill its obligations.



- (4) It shall fully comply with applicable laws in the performance of this Agreement.

Each Party agrees to notify the other promptly if any of the above representations cease to remain true.

13. DISPUTE RESOLUTION

- (1) Any dispute arising out of or relating to this MoU shall first be resolved through mutual discussions.
- (2) If unresolved, the dispute shall be referred to arbitration in accordance with the provisions of the Indian Arbitration and Conciliation Act, 1996, as amended from time to time.
- (3) The venue of arbitration shall be Kancheepuram and the proceedings shall be conducted in English.

IN WITNESS WHEREOF, intending to be legally bound, the parties have entered into this Agreement effective as of the date first written above.

Sri Chandrasekharendra Saraswathi Viswa Mahavidyalaya

By : 
Name: Dr.G.Sriram
Title : Registrar i/c
Date : 10/07/26



WaferLead Pte. Ltd.

By : 
Name: Dr. Sunil Wickramanayaka
Title : CEO
Date : 8th July 2026